

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (original): A resist composition comprising (A) a resin component, (B) a photopolymerization initiator, (C) water and (D) an organic solvent, wherein the organic solvent (D) contains:

(D-1) at least one organic solvent selected from the group consisting of an α -hydroxycarboxylate ester, a β -alkoxycarboxylate ester, a 1,3-diol compound and a 1,3-diol compound derivative, and

(D-2) an organic solvent having a hydroxyl group other than (D-1).

2. (original): The resist composition according to claim 1, wherein (D-1) is an α -hydroxycarboxylate ester.

3. (original): The resist composition according to claim 2, wherein the α -hydroxycarboxylate ester is a lactate ester.

4. (currently amended): A method of producing a resist-coated substrate, which comprises dipping an insulating substrate comprising a conductive metal in the resist composition according to claim 1 ~~any one of claims 1 to 3~~.

5. (currently amended): A method of producing a print circuit board, which comprises using the resist composition according to claim 1 ~~any one of claims 1 to 3~~.

6. (original): A resist composition for dip coating comprising (A) a resin component, (B) a photopolymerization initiator, (C) water and (D) an organic solvent, wherein the organic solvent (D) contains:

(D-1) at least one organic solvent selected from the group consisting of an α -hydroxycarboxylate ester, a β -alkoxycarboxylate ester, a 1,3-diol compound and a 1,3-diol compound derivative.

7. (original): A method of producing a resist-coated substrate, which comprises dipping an insulating substrate comprising a conductive metal in the resist composition according to claim 6.

8. (original): A method of producing a print circuit board, which comprises using the resist composition according to claim 6.

9. (new): A method of producing a resist-coated substrate, which comprises dipping an insulating substrate comprising a conductive metal in the resist composition according to claim 2.

10. (new): A method of producing a print circuit board, which comprises using the resist composition according to claim 2.

11. (new): A method of producing a resist-coated substrate, which comprises dipping an insulating substrate comprising a conductive metal in the resist composition according to claim 3.

12. (new): A method of producing a print circuit board, which comprises using the resist composition according to claim 3.